

General Description

The MY10N10C use advanced SGT MOSFET technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is specially designed to get better ruggedness and suitable

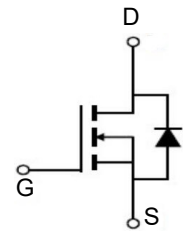
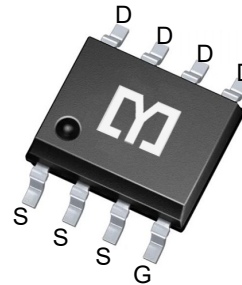


: YUhi fYg

V_{DS}	100	V
I_D	10	A
$P_D(T_A=25^\circ\text{C})$	3.5	W
T_{FUTOP}	>18	°C

Application

- Consumer electronic power supply
- Motor control
- Synchronous-rectification
- Isolated DC
- Synchronous-rectification applications



DUW U[Y A Uf]b[UbX CfXYf]b[-bZfa U]cb

DfcXi Wi-8	DUW	A Uf]b[E lmfD7 GŁ
MY10N10C	ÚÚÚĚ	018IN	HĚĚĚ

5 Vgc`i h`A U]a i a `FU]b[g`fH,1&) °C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	100	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾	I_D	10	A
Pulsed drain current ²⁾	I_D , pulse	30	A
Power dissipation ³⁾	P_D	3.5	W
Single pulsed avalanche energy ⁵⁾	EAS	30	mJ
Operation and storage temperature	T_{stg} , T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	35.7	°C/W

Max.

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV _{DSS}	100			V	V _{GS} =0 V, I _D =250 μA
Gate threshold voltage	V _{GS(th)}	1.0		2.5	V	V _{DS} =V _{GS} , I _D =250 μA
Drain-source on-state resistance	R _{DS(ON)}			18	mΩ	V _{GS} =10 V, I _D =8 A
Drain-source on-state resistance	R _{DS(ON)}			26	mΩ	V _{GS} =4.5 V, I _D =6 A
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =20 V
				-100		V _{GS} =-20 V
Drain-source leakage current	I _{DSS}			1	μA	V _{DS} =100 V, V _{GS} =0 V
Input capacitance	C _{iss}		1190.6		pF	V _{GS} =0 V, V _{DS} =50 V, f=1 MHz
Output capacitance	C _{oss}		194.6		pF	
Reverse transfer capacitance	C _{rss}		4.1		pF	
Turn-on delay time	t _{d(on)}		17.8		ns	V _{GS} =10 V, V _{DS} =50 V, R _G =2.2 Ω, I _D =10 A
Rise time	t _r		3.9		ns	
Turn-off delay time	t _{d(off)}		33.5		ns	
Fall time	t _f		3.2		ns	
Total gate charge	Q _g		19.8		nC	I _D =8 A, V _{DS} =50 V, V _{GS} =10 V
Gate-source charge	Q _{gs}		2.4		nC	
Gate-drain charge	Q _{gd}		5.3		nC	
Gate plateau voltage	V _{plateau}		3.2		V	
Diode forward current	I _S			8	A	V _{GS} <V _{th}
Pulsed source current	I _{SP}			32		
Diode forward voltage	V _{SD}			1.3	V	I _S =8 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		50.2		ns	I _S =8 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		95.1		nC	
Peak reverse recovery current	I _{rrm}		2.5		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=50 V, R_G=25 Ω, L=0.3 mH, starting T_J=25 °C.

Typical Characteristics

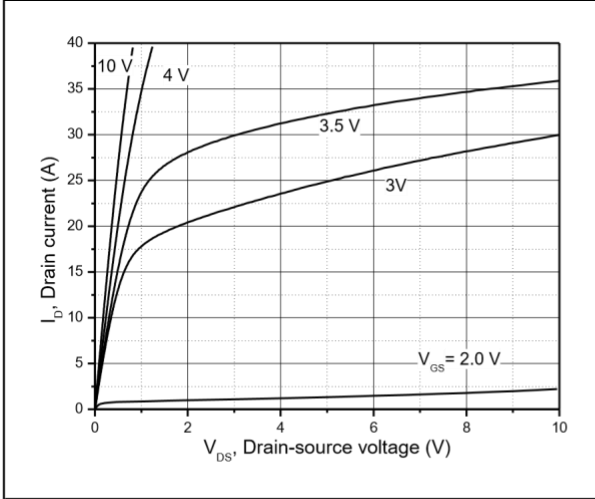


Figure 1, Typ. output characteristics

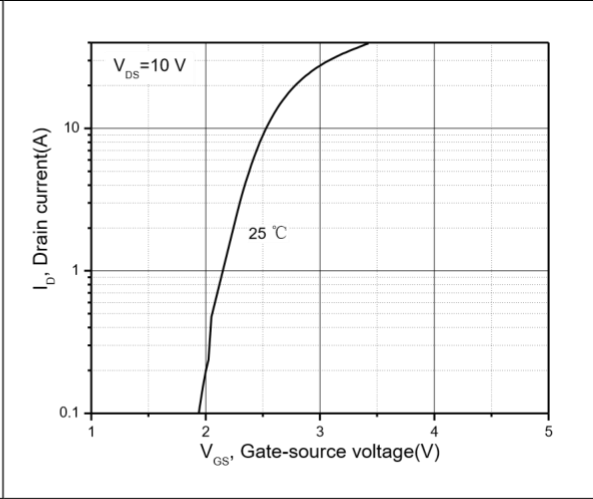


Figure 2, Typ. transfer characteristics

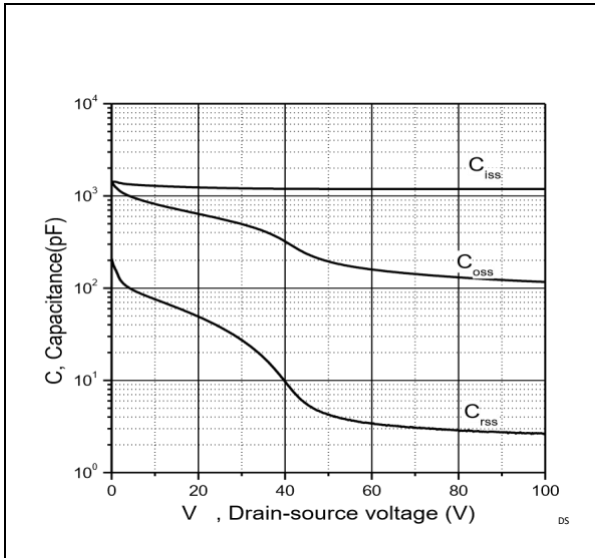


Figure 3, Typ. capacitances

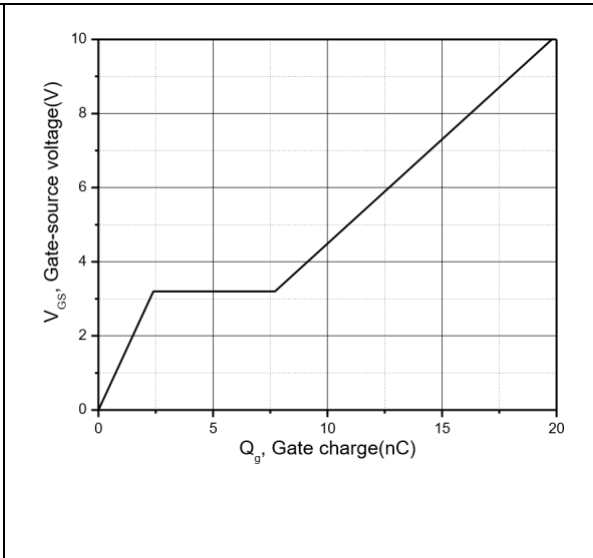


Figure 4, Typ. gate charge

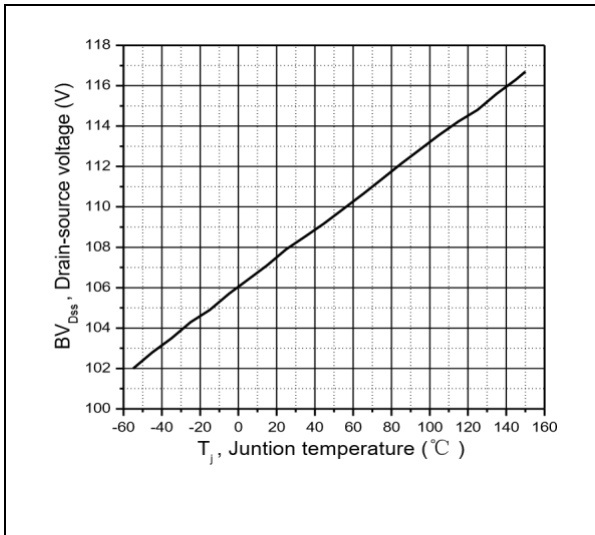


Figure 5, Drain-source breakdown voltage

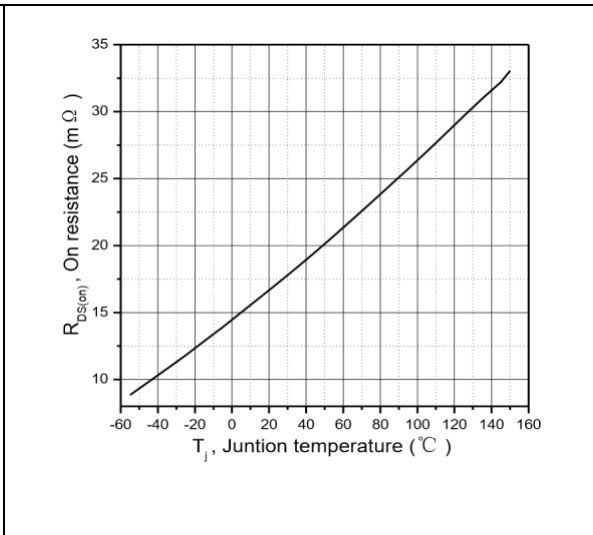


Figure 6, Drain-source on-state resistance

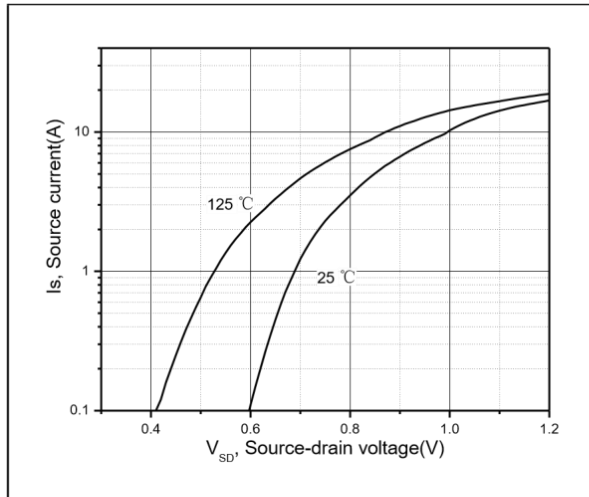


Figure 7, Forward characteristic of body diode

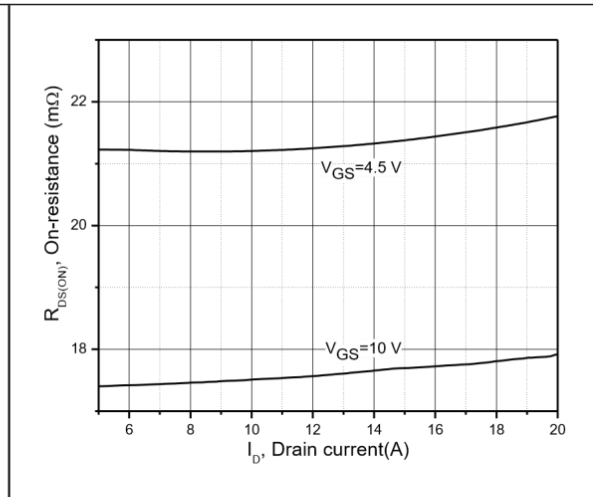


Figure 8, Drain-source on-state resistance

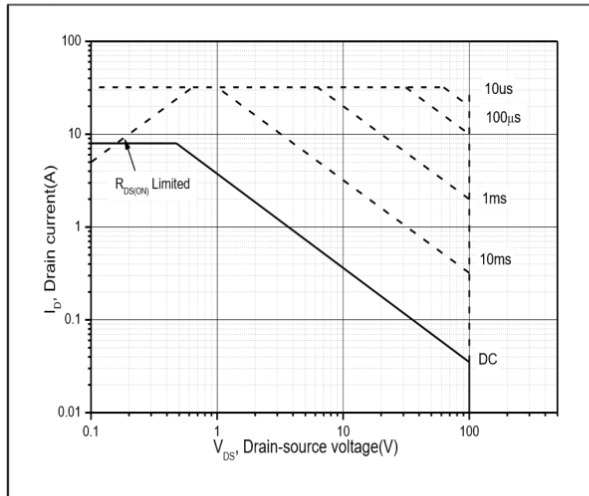


Figure 9, Safe operation area $T_C=25\text{ }^\circ\text{C}$

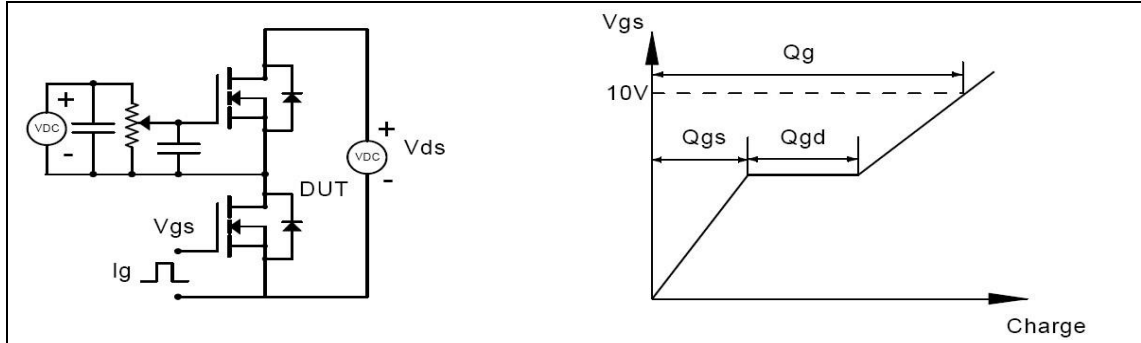


Figure 1, Gate charge test circuit & waveform

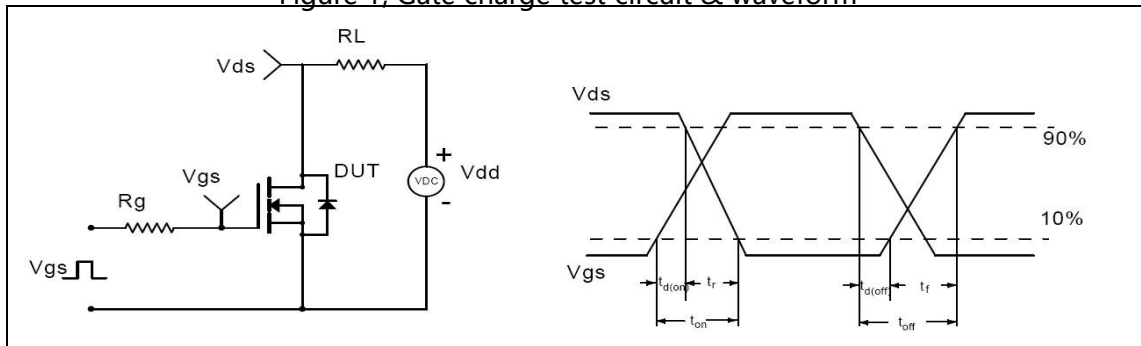


Figure 2, Switching time test circuit & waveforms

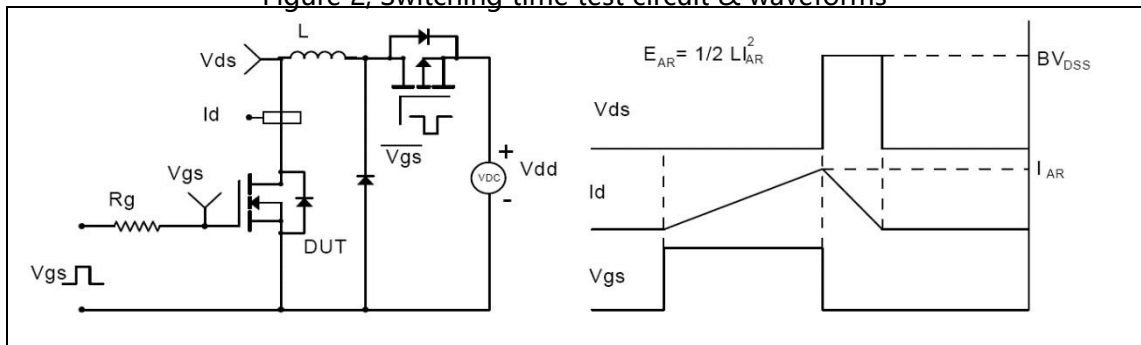


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

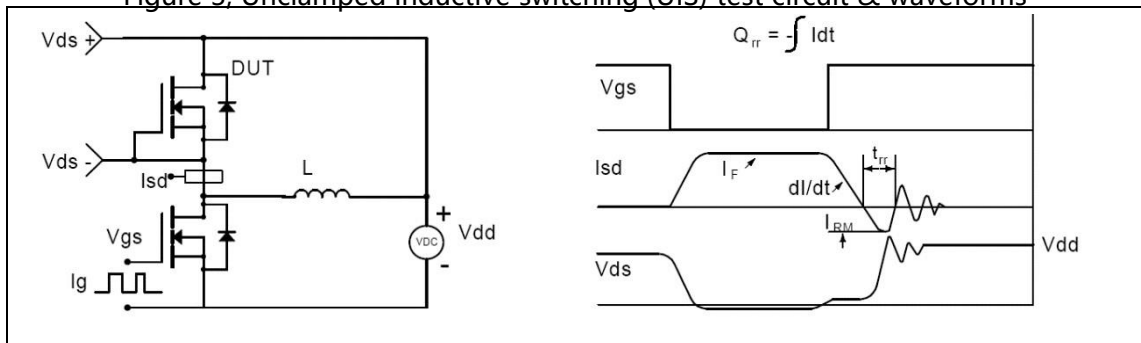


Figure 4, Diode reverse recovery test circuit & waveforms

Package Mechanical Data-SOP-8

